RELIABILITY REPORT

FOR

MAX9945AUA+

PLASTIC ENCAPSULATED DEVICES

October 6, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX9945AUA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX9945 operational amplifier features an excellent combination of low operating power and low input voltage noise. In addition, MOS inputs enable the MAX9945 to feature low input bias currents and low input current noise. The device accepts a wide supply voltage range from 4.75V to 38V and draws a low 400µA quiescent current. The MAX9945 is unity-gain stable and is capable of rail-to-rail output voltage swing. The MAX9945 is ideal for portable medical and industrial applications that require low noise analog front-ends for performance applications such as photodiode transimpedance and chemical sensor interface circuits. The MAX9945 is available in both an 8-pin µMAX® and a space-saving, 6-pin TDFN package, and is specified over the automotive operating temperature range (-40°C to +125°C).

II. Manufacturing Information

A. Description/Function:	38V, Low-Noise, MOS-Input, Low-Power Op Amp
B. Process:	BCD8
C. Number of Device Transistors:	78
D. Fabrication Location:	Oregon
E. Assembly Location:	Philippines, Thailand, Malaysia
F. Date of Initial Production:	1/24/2009

III. Packaging Information

A. Package Type:	8-pin uMAX	6-pin TDFN 3x3
B. Lead Frame:	Copper	Copper
C. Lead Finish:	100% matte Tin	100% matte Tin
D. Die Attach:	Conductive	Conductive
E. Bondwire:	Au (1 mil dia.)	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3496	#05-9000-3495
H. Flammability Rating:	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1	Level 1
J. Single Layer Theta Ja:	221°C/W	55°C/W
K. Single Layer Theta Jc:	41.9°C/W	8.5°C/W
L. Multi Layer Theta Ja:	206.3°C/W	42°C/W
M. Multi Layer Theta Jc:	41.9°C/W	8.5°C/W

IV. Die Information

A. Dimensions:	49 X 86 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 48 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.4 \times 10^{-9}$

$\lambda = 22.4$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the BCD8 Process results in a FIT Rate of 0.06 @ 25C and 1.08 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The OY35 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA, 1.5x VCCMax Overvoltage per JESD78.

Table 1

Reliability Evaluation Test Results

MAX9945AUA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data